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February 2011

# NC7SZ34 TinyLogic<sup>®</sup> UHS Buffer

#### **Features**

- Ultra-High Speed: t<sub>PD</sub> 2.4ns (Typical) into 50pF at 5V V<sub>CC</sub>
- High Output Drive: ±24mA at 3V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range: 1.65V to 5.5V
- Matches Performance of LCX Operated at 3.3V V<sub>CC</sub>
- Power-Down High-Impedance Inputs / Outputs
- Proprietary Noise / EMI Reduction Circuitry
- WLCSP Package

### Description

The NC7SZ34 is a single buffer from Fairchild's Ultra-High Speed (UHS) series of TinyLogic®. The device is fabricated with advanced CMOS technology to achieve ultra-high speed with high output drive, while maintaining low static power dissipation over a broad  $V_{\rm CC}$  operating range of 1.65V to 5.5V  $V_{\rm CC}$ . The inputs and output are high-impedance when  $V_{\rm CC}$  is 0V. Inputs tolerate voltages up to 7V, independent of  $V_{\rm CC}$  operating voltage.

#### **Related Resources**

- AN-5055 Portability and Ultra Low Power TinyLogic<sup>®</sup>
- MS-503 Family Characteristics TinyLogic<sup>®</sup> HS/HST and UHS Series

# **Ordering Information**

Part Number	Top Mark	Package	Packing Method
NC7SZ34UCX	KJ	4-Lead, Wafer-Level Chip Scale 0.76x0.76x0.5mm Wafer-Level Chip-Scale Package (WLCSP)	3000 Units on Tape & Reel

# **Pin Configurations**

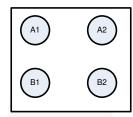


Figure 1. WLCSP (Top View)

# **Pin Definitions**

WLCSP	Name	Description
A1	Α	Input
A2	VCC	Power Supply
B1	GND	Ground
B2	Υ	Output

# **Function Table**

Y = A

Inputs	Output
Α	Y
LOW Logic Level	LOW Logic Level
HIGH Logic Level	HIGH Logic Level

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Para	ameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage		-0.5	7.0	V
V <sub>IN</sub>	DC Input Voltage		-0.5	7.0	V
V <sub>OUT</sub>	DC Output Voltage		-0.5	7.0	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < -0.5V		-50	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < -0.5V		-50	mA
I <sub>OUT</sub>	DC Output Current			±50	mA
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current			±50	mA
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C
TJ	Junction Temperature Under B	ias		+150	°C
TL	Junction Lead Temperature (So	oldering, 10 Seconds)		+260	°C
P <sub>D</sub>	Power Dissipation at +85°C			200	mW
ECD	Human Body Model, JEDEC:JE	SD22-A114		4000	
ESD	Charge Device Model, JEDEC:	JESD22-C101		2000	V

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V	Supply Voltage Operating		1.65	5.50	V
V <sub>CC</sub>	Supply Voltage Data Retention		1.5	5.5	]
V <sub>IN</sub>	Input Voltage		0	5.5	V
V <sub>OUT</sub>	Output Voltage		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature		-40	+85	°C
		V <sub>CC</sub> at 1.8V, 2.5V ±0.2V	0	20	
$t_r, t_f$	Input Rise and Fall Times	V <sub>CC</sub> at 3.3V ±0.3V	0	10	ns/V
		V <sub>CC</sub> at 5.0V ±0.5V	0	5	
$\theta_{JA}$	Thermal Resistance			80	°C/W

#### Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

# **DC Electrical Characteristics**

Or made al	Dawamatan	N/	O a maliki a ma		T <sub>A</sub> =25°(		T <sub>A</sub> =-40	to 85°C	11
Symbol	Parameter	V <sub>cc</sub>	Conditions	Min.	Тур.	Max.	Min.	Max.	Unit
.,	HIGH Level	1.65 to 1.95		0.65V <sub>CC</sub>			0.65V <sub>CC</sub>		
$V_{IH}$	Input Voltage	2.30 to 5.50		0.70V <sub>CC</sub>			0.70V <sub>CC</sub>		V
\/	LOW Level	1.65 to 1.95				0.35V <sub>CC</sub>		0.35V <sub>CC</sub>	V
$V_{IL}$	Input Voltage	2.30 to 5.50				0.30V <sub>CC</sub>		0.30V <sub>CC</sub>	\ \
		1.65		1.55	1.65				
		1.80		1.70	1.80		1.70		
		2.30	V <sub>IN</sub> =V <sub>IH</sub> , I <sub>OH</sub> = -100μΑ	2.20	2.30		2.20		
		3.00	Τοομπ	2.90	3.00		2.90		
V	HIGH Level	4.50		4.40	4.50		4.40		V
$V_{OH}$	Output Voltage	1.65	I <sub>OH</sub> =-4mA	1.29	1.52	4	1.29		
		2.30	I <sub>OH</sub> =-8mA	1.90	2.15		1.90		
		3.00	I <sub>OH</sub> =-16mA	2.40	2.80		2.40		
		3.00	I <sub>OH</sub> =-24mA	2.30	2.68		2.30		
		4.50	$I_{OH}$ =-32mA	3.80	4.20		3.80		
		1.65			0.00	0.10		0.10	
		1.80			0.00	0.10		0.10	
		2.30	$V_{IN}=V_{IL}$ , $I_{OL}=100\mu A$		0.00	0.10		0.10	
		3.00	10[=100μ/τ		0.00	0.10		0.10	
V	LOW Level	4.50			0.00	0.10		0.10	V
$V_{OL}$	Output Voltage	1.65	I <sub>OL</sub> =4mA		0.08	0.24		0.24	
		2.30	I <sub>OL</sub> =8mA		0.10	0.30		0.30	
		3.00	I <sub>OL</sub> =16mA		0.15	0.40		0.40	
		3.00	I <sub>OL</sub> =24mA		0.22	0.55		0.55	
		4.50	I <sub>OL</sub> =32mA		0.22	0.55		0.55	
I <sub>IN</sub>	Input Leakage Current	0 to 5.5	$0 \leq V_{IN} \leq 5.5V$			±1		±10	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	0	V <sub>IN</sub> or V <sub>OUT</sub> =5.5V			1		10	μΑ
I <sub>cc</sub>	Quiescent Supply Current	1.65 to 5.50	V <sub>IN</sub> =5.5V, GND			1.0	· y	10	μΑ

### **AC Electrical Characteristics**

Symbol	Symbol Parameter		V <sub>CC</sub> Conditions		T <sub>A</sub> =25°C		T <sub>A</sub> =-40 to 85°C		Unit	Figure
				Min.	Тур.	Max.	Min.	Max.	S	
		1.65		2.0	5.3	11.4	2.0	12.0		
	1.80	1.80		2.0	4.4	9.5	2.0	10.0		
		2.5 ±0.2	$C_L=15pF$ , $R_L=1M\Omega$	0.8	2.9	6.5	0.8	7.0		
$t_{PLH},t_{PHL}$	Propagation Delay	3.3 ±0.3		0.5	2.1	4.5	0.5	4.7	ns	Figure 2 Figure 3
		5.0 ±0.5		0.5	1.8	3.9	0.5	4.1		i igai o o
		3.3 ±0.3	C <sub>L</sub> =50pF,	1.5	2.9	5.0	1.5	5.2		
		5.0 ±0.5	$R_L=500\Omega$	0.8	2.4	4.3	0.8	4.5		
C <sub>IN</sub>	Input Capacitance	0.00			2.0				pF	
	Power Dissipation	3.30			12.9				ρE	Figure 4
$C_{PD}$	Capacitance <sup>(2)</sup>	5.00			15.6		·		pF	rigule 4

#### Note:

2. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output lading and operating at 50% duty cycle. C<sub>PD</sub> is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub>=(C<sub>PD</sub>)(V<sub>CC</sub>)(f<sub>IN</sub>)+(I<sub>CC</sub>static).

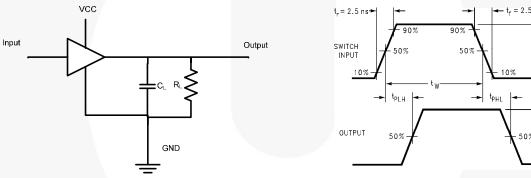


Figure 2. AC Test Circuit

Figure 3. AC Waveforms

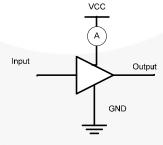
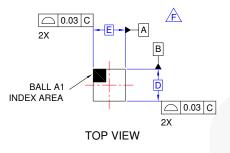


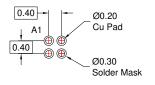
Figure 4. I<sub>CCD</sub> Test Circuit

#### Note:

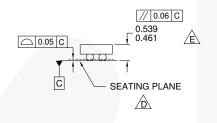
3. Input=AC Waveform;  $t_r=t_f=1.8$ ns; Frequency =10MHz; Duty Cycle =50%.

# **Physical Dimensions**





#### RECOMMENDED LAND PATTERN (NSMD PAD TYPE)





#### NOTES:

SIDE VIEWS

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 1994.



PACKAGE NOMINAL HEIGHT IS 500 MICRONS ±39 MICRONS (461-539 MICRONS).

FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

G. DRAWING FILNAME: MKT-UC004AFrev1.

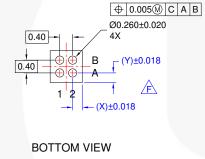


Figure 5. 4-Lead, Wafer-Level Chip Scale 0.76x0.76x0.5mm Wafer-Level Chip-Scale Package (WLCSP)

Product	D	E	X	Υ
NC7SZ34UCX	0.76 +/-0.030	0.76 +/-0.030	0.18	0.18

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

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#### **Tape and Reel Specifications**

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: <a href="http://www.fairchildsemi.com/packaging/SOT23-5L">http://www.fairchildsemi.com/packaging/SOT23-5L</a> tr.pdf.

Package Designator	Tape Section	Cavity Number	<b>Cavity Status</b>	Cover Type Status	
	Leader (Start End)	125 (Typical)	Empty	Sealed	
UCX	Carrier	3000	Filled	Sealed	
	Trailer (Hub End)	75 (Typical)	Empty	Sealed	





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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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